

POLISHING APPARATUS AND POLISHING METHOD

ABSTRACT OF THE DISCLOSURE

5 A novel polishing apparatus which determines a polishing end point of a substrate on the basis of a strain of a constituent element of the polishing apparatus caused by friction between a substrate such as a wafer and a polishing pad. The polishing apparatus includes a rotatable polishing table which supports a polishing pad, a polishing head which presses the substrate against the polishing pad, a rotating shaft connected to the polishing head, a support structure
10 which rotatably supports the rotating shaft, a strain measuring instrument which measures a strain of the support structure, and an end point detector which determines a polishing end point of the substrate on the basis of a change in the strain. The strain measuring instrument includes at least one strain sensor fixed to the support structure.

15 FIG. 1